LNJ026X8BRA1

Hight Bright Surface Mounting Chip LED

UTSS Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit				
Power dissipation	P _D	40	mW				
Forward current	$I_{\rm F}$	10	mA				
Pulse forward current *	I_{FP}	40	mA				
Reverse voltage	V _R	5	V				
Operating ambient temperature	T _{opr}	-30 to +85	°C				
Storage temperature	T _{stg}	-40 to +100	°C				

Lighting Color

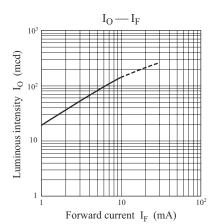
• White

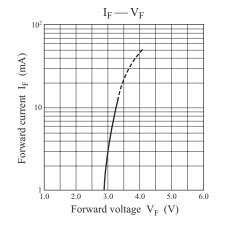
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

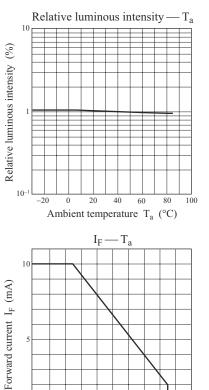
Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_F = 5 \text{ mA}$	36	80	170	mcd
Reverse current	I _R	$V_R = 5 V$			10	μΑ
Forward voltage	$V_{\rm F}$	$I_{\rm F} = 5 {\rm mA}$		3.1	3.7	V
Chromaticity coordinates —	х	$I_{\rm F} = 5 {\rm mA}$	0.250		0.330	
	у	$I_{\rm F} = 5 {\rm mA}$	0.226		0.359	

Note) *: Measurement tolerance: ±20%







0

20

40

60

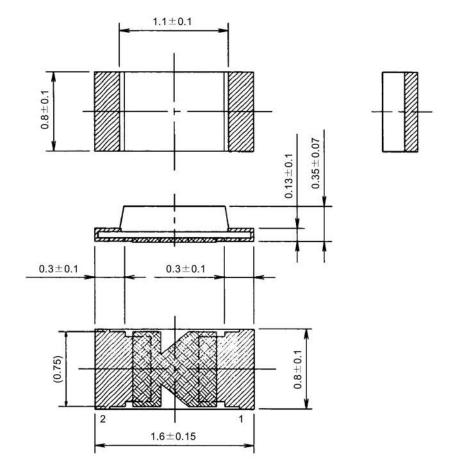
Ambient temperature T_a (°C)

80

100

Package (Unit: mm)

KLTFTN2K2600



• Pin name

1: Anode 2: Cathode

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